

**Embedded Computing Platform**



**HVP300**

**Embedded Computing Platform**

**User Manual**

Rev 1.1

Date: January 24<sup>th</sup>, 2017

## Embedded Computing Platform

### Revision History

Revision	Date	Description
0.1	August 3, 2016	Preliminary
1.0	August 22, 2016	Official release
1.1	January 24, 2017	Added LTE module installation Modified power input voltage Modified operating temperature Added PoE configuraiton description Added warning statement in the installation precaution Added wall mounting section

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### Online Resources

The listed websites are links to the on-line product information and technical support.

Resource	Website
Lanner	<a href="http://www.lannerinc.com">www.lannerinc.com</a>
Product Resources	<a href="http://www.lannerinc.com/support/download-center">www.lannerinc.com/support/download-center</a>
RMA	<a href="http://eRMA.lannerinc.com">http://eRMA.lannerinc.com</a>

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### Compliances and Certification

#### CE Certification

This product has passed the CE test for environmental specifications. Test conditions for passing included the equipment being operated within an industrial enclosure. In order to protect the product from being damaged by ESD (Electrostatic Discharge) and EMI leakage, we strongly recommend the use of CE-compliant industrial enclosure products.

#### FCC Class A Certification

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

#### EMC Notice

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case users will be required

to correct the interference at their own expense.

### Safety Guidelines

- Follow these guidelines to ensure general safety:
- Keep the chassis area clear and dust-free before, during and after installation.
- Do not wear loose clothing or jewelry that could get caught in the chassis. Fasten your tie or scarf and roll up your sleeves.
- Wear safety glasses/goggles if you are working under any conditions that might be hazardous to your eyes.
- Do not perform any action that creates a potential hazard to people or makes the equipment unsafe.
- Disconnect all power by turning off the power and unplugging the power cord before installing or removing a chassis or working near power supplies
- Do not work alone if potentially hazardous conditions exist.
- Never assume that power is disconnected from a circuit; always check the circuit.

### LITHIUM BATTERY CAUTION:

Risk of explosion could occur if battery is replaced by an incorrect type. Please dispose of used batteries according to the recycling instructions of your country.

### Operating Safety

- Electrical equipment generates heat. Ambient air temperature may not be adequate to cool equipment to acceptable operating temperatures without adequate circulation. Be sure that the room in which you choose to operate your system has adequate air circulation.
- Ensure that the chassis cover is secure. The chassis design allows cooling air to circulate effectively. An open chassis permits air leaks, which may interrupt and redirect the flow of cooling air from internal components.

Electrostatic discharge (ESD) can damage equipment and impair electrical circuitry. ESD damage occurs when electronic components are improperly handled and can result in complete or intermittent failures. Be sure to follow ESD-prevention procedures when removing and replacing components to avoid these problems.

- Wear an ESD-preventive wrist strap, ensuring that it makes good skin contact. If no wrist strap is available, ground yourself by touching the metal part of the chassis.
- Periodically check the resistance value of the antistatic strap, which should be between 1 and 10 megohms (Mohms).
- Installation only by a trained electrician or only by an electrically trained person who knows all the applied or related installation and device specifications..
- Do not carry the handle of power supplies when moving to other place.

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- The machine can only be used in a fixed location such as labs or computer facilities.

### Mounting Installation Environment Precaution

1. Elevated Operating Ambient - If installed in a closed or multi-unit rack assembly, the operating ambient temperature of the rack environment may be greater than room ambient. Therefore, consideration should be given to installing the equipment in an environment compatible with the maximum ambient temperature (T<sub>ma</sub>) specified by the manufacturer.
2. Reduced Air Flow - Installation of the equipment in a rack should be such that the amount of air flow required for safe operation of the equipment is not compromised.
3. Mechanical Loading - Mounting of the equipment in the rack should be such that a hazardous condition is not achieved due to uneven mechanical loading.
4. Circuit Overloading - Consideration should be given to the connection of the equipment to the supply circuit and the effect that overloading of the circuits might have on over-current protection and supply wiring. Appropriate consideration of equipment nameplate ratings should be used when addressing this concern.
5. Reliable Earthing - Reliable earthing of rack-mounted equipment should be maintained. Particular attention should be given to supply connections other than direct connections to the branch circuit (e.g. use of power strips)."
6. **Warning:** the unit must be installed indoors. The unit, AC power adapter, and its cables are not designed for outdoor use.

### Consignes de sécurité

Suivez ces consignes pour assurer la securite generale :

- Laissez la zone du chassis propre et sans poussiere pendant et apres l'installation.
- Ne portez pas de vetements amples ou de bijoux qui pourraient etre pris dans le chassis. Attachez votre cravate ou echarpe et remontez vos manches.
- Portez des lunettes de securite pour proteger vosmyeux.
- N'effectuez aucune action qui pourrait creer un dangermpour d'autres ou rendre l'equipement dangereux.
- Coupez completement l'alimentation en eteignant l'alimentation et en debranchant le cordon d'alimentation avant d'installer ou de retirer un chassis ou de travailler a proximite de sources d'alimentation.
- Ne travaillez pas seul si des conditions dangereuses sont presentes.
- Ne considerez jamais que l'alimentation est coupee d'un circuit, verifiez toujours le circuit. Cet appareil genere, utilise et emet une energie radiofrequence et, s'il n'est pas installe et utilise conformement aux instructions des fournisseurs de composants sans fil, il risque de provoquer des

interferences dans les communications radio.

### Avertissement concernant la pile au lithium

- Risque d'explosion si la pile est remplacée par une autre d'un mauvais type.
- Jetez les piles usagées conformément aux instructions.
- L'installation doit être effectuée par un electricien formé ou une personne formée à l'électricité connaissant toutes les spécifications d'installation et d'appareil du produit.
- Ne transportez pas l'unité en la tenant par le câble d'alimentation lorsque vous déplacez l'appareil.
- La machine ne peut être utilisée qu'à un lieu fixe comme en laboratoire, salle d'ordinateurs ou salle de classe.

### Sécurité de fonctionnement

- L'équipement électrique génère de la chaleur. La température ambiante peut ne pas être adéquate pour refroidir l'équipement à une température de fonctionnement acceptable sans circulation adaptée. Vérifiez que votre site propose une circulation d'air adéquate.
- Vérifiez que le couvercle du châssis est bien fixé. La conception du châssis permet à l'air de refroidissement de bien circuler. Un châssis ouvert laisse l'air s'échapper, ce qui peut interrompre et rediriger le flux d'air frais destiné aux composants internes.
- Les décharges électrostatiques (ESD) peuvent endommager l'équipement et gêner les circuits électriques. Des dégâts d'ESD surviennent lorsque des composants électroniques sont mal manipulés et peuvent causer des pannes totales ou intermittentes. Suivez les procédures de prévention d'ESD lors du retrait et du remplacement de composants.

- Portez un bracelet anti-ESD et veillez à ce qu'il soit bien au contact de la peau. Si aucun bracelet n'est disponible, reliez votre corps à la terre en touchant la partie métallique du châssis. Vérifiez régulièrement la valeur de résistance du bracelet antistatique, qui doit être comprise entre 1 et 10 mégohms (Mohms).

### Consignes de sécurité électrique

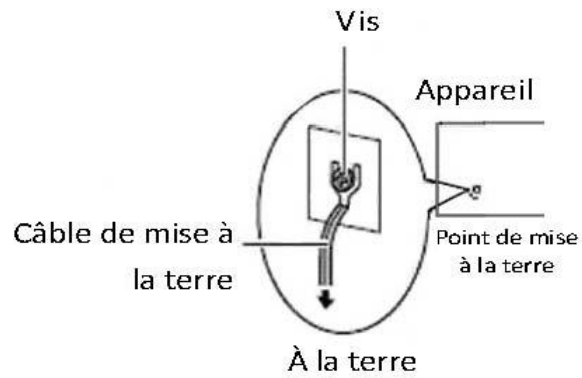
- Avant d'allumer l'appareil, reliez le câble de mise à la terre de l'équipement à la terre.
- Une bonne mise à la terre (connexion à la terre) est très importante pour protéger l'équipement contre les effets néfastes du bruit externe et réduire les risques d'électrocution en cas de foudre.
- Pour désinstaller l'équipement, débranchez le câble de mise à la terre après avoir éteint l'appareil.
- Un câble de mise à la terre est requis et la zone reliant les sections du conducteur doit faire plus de 4 mm<sup>2</sup> ou 10 AWG.

### Procédure de mise à la terre pour source d'alimentation CC

- Desserrez la vis du terminal de mise à la terre.
- Branchez le câble de mise à la terre à la terre.
- L'appareil de protection pour la source d'alimentation

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CC doit fournir 30 A de courant. Cet appareil de protection doit être branché à la source d'alimentation avant l'alimentation CC.



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# Chapter 1: Introduction

Thank you for choosing HVP300. This industrial embedded system is empowered by Intel® Core™ i7-6600U SoC processors (codenamed Skylake-U). The I/O features include four RS-232/422/485 serial ports, four USB 3.0, two USB 2.0 ports and two HDMI ports. For networking communications, the HVP300 comes with two 10/100/1000 Mbps Ethernet ports and four PoE ports for even greater flexibility.

### Product Features:

- Intel® Core™ i7-6600U SoC
- 2 x DDR3L 1333/1600MHz SO-DIMM sockets supporting up to 16GB
- Intel® HD Graphics
- 2x HDMI display output ports
- 6x RJ45 (HVP300) or 2x RJ45 & 4x PoE (HVP300P)
- 4x USB 3.0 and 2x USB 2.0
- 2x 2.5" HDD/SSD with RAID 0/1
- 4x Serial Ports with RS-232/422/485 signals
- 0°C ~ +40°C Wide Operating Temperature Range
- 2 x mini-PCIe sockets (1 x full-size and 1 x half-size) with PCIe and USB signals (the full-size socket is compatible with LTE module)
- 1 x mSATA socket for internal storage

Please refer to the following table for detailed specifications

## Specifications

<b>Processor</b>	Onboard Intel Skylake-U SoC processor options: Intel® Core™ i7-6600U (15W)
<b>Memory</b>	2x DDR3L 1333/1600MHz SO-DIMM sockets supporting up to 16GB
<b>BIOS</b>	AMI SPI Flash BIOS
<b>Serial</b>	4 x D-Sub9 COM ports with RS-232/422/485 signals
<b>USB</b>	4 x USB 3.0 Type-A ports in dual double-stacked form 2 x USB 2.0 Type-A ports in double-stacked form
<b>Display</b>	Intel Integrated HD Graphic Engine 2 x HDMI ports
<b>Storage</b>	1x mSATA mini socket 1 x dual 2.5" SATA HDD/SSD drive bay

## Embedded Computing Platform

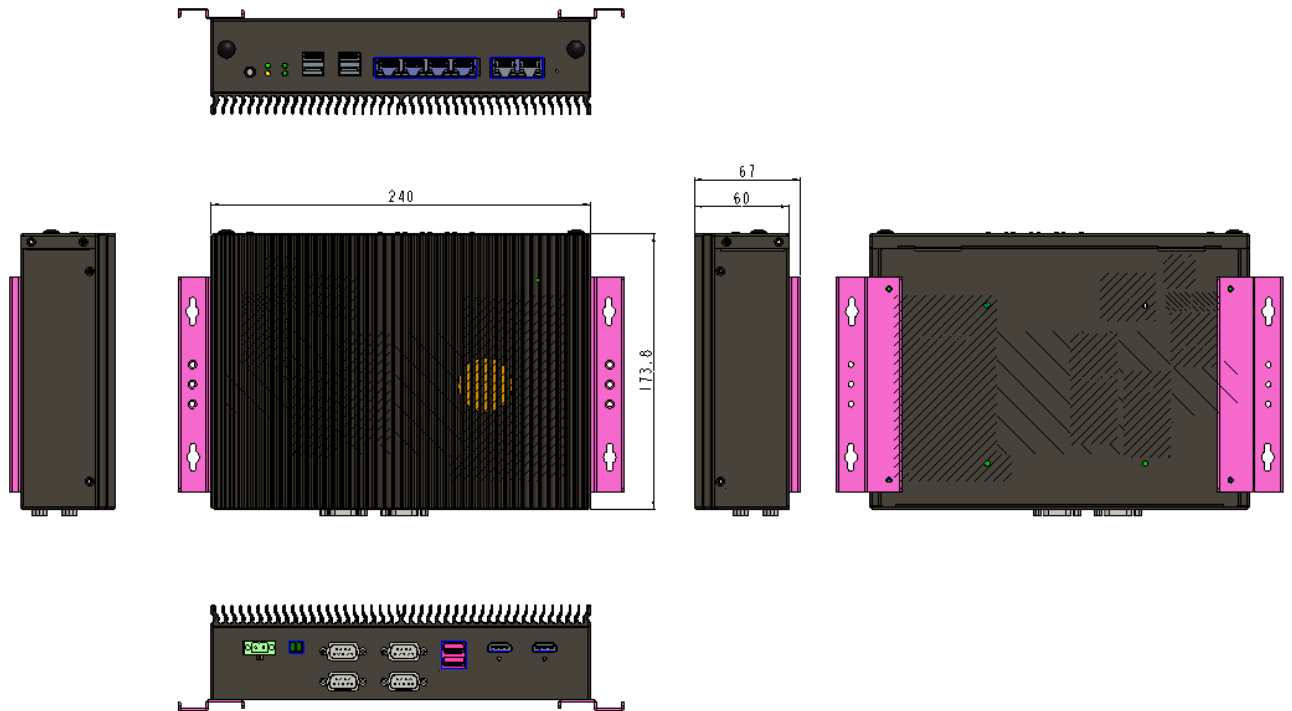
<b>Expansion</b>		1x standard mini-PCI express socket (full size) with SIM card reader, compatible with LTE module 1x half-sized mini-PCI express socket 1x mSATA mini socket
<b>Antenna</b>		2 x SMA antenna holes (sealed by default)
<b>Networking</b>	Ethernet Controller	1x Intel i219 5x Intel i210
	Ethernet Ports	6 x RJ-45 10/100/1000Mbps ports
	PoE	4 x RJ-45 LAN ports with PoE function
<b>LEDs</b>		2 x LED for Power-on status(Green) and Storage access status(Yellow) 2 x LED for 3G & WiFi communication access
<b>Physical Characteristics</b>	Dimensions	164.5 x 143.0 x 30.0, unit: mm
	Mounting	Wall mount, VESA mount
<b>Power</b>	Input	1x 2pin terminal block, support DC +24V input
	Adapter	24V/5A, 120W with PoE
<b>Reliability Tool</b>	Automatic Reboot Setting	Lanner Watchdog Timer 1~255 level per second or minute
<b>Environment</b>	Operating Temperature	0°C - 40°C
	Non-operating Temperature	-20 - 70°C
	Humidity	5 to 95% (non-condensing)
	Green	RoHS
<b>Operating System Supported</b>		WES 7 E/P, Win 7 Pro FES, WE 8.1 Industry Pro, Win10 IOT
<b>Standards &amp; Regulations</b>	EMC	CE, FCC Class A

## Ordering Information

<b>HVP300</b>	Embedded industrial PC with Intel i7-6600U w/ 4-ports PoE
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## Chapter 2: System Overview

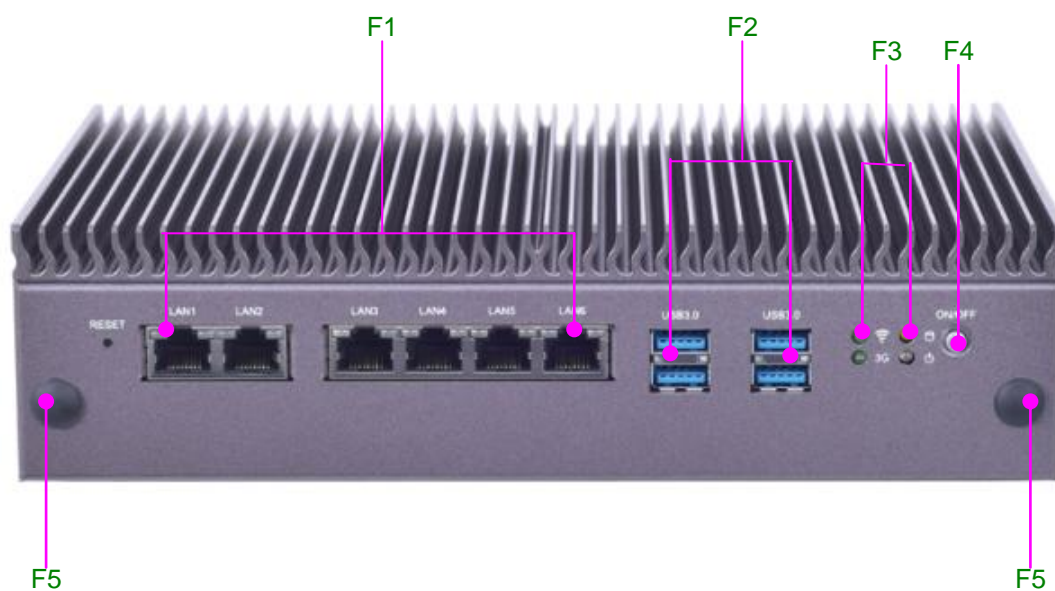
### Mechanical Drawing



Unit: mm

## Embedded Computing Platform

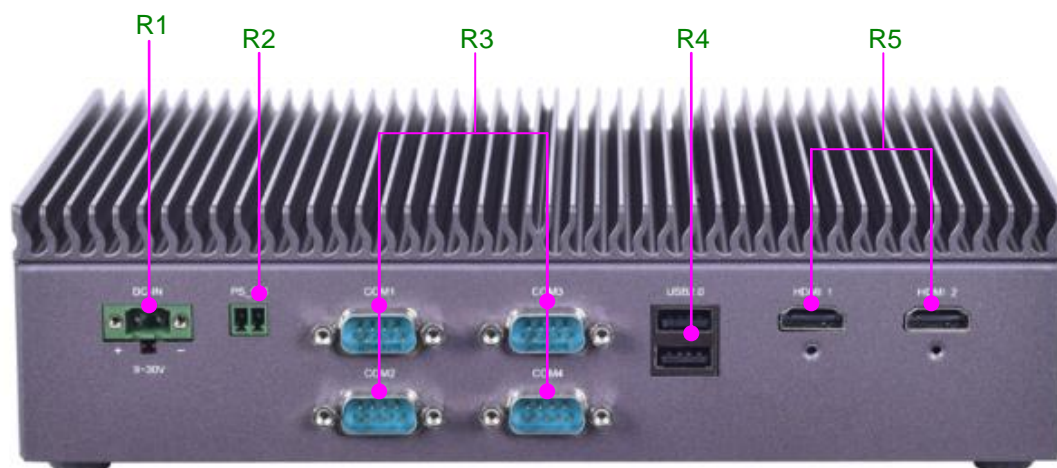
### Front I/Os



F1 LAN	6 x 10/100/1000 mbps RJ-45 LAN ports LAN3-LAN6 are PoE ports
F2 USB 3.0	4 x USB3.0 Type-A ports in dual double-stacked form
F3 LED	2 x LED for Power-on status(Green) and Storage access status(Yellow) 2 x LED for 3G & WiFi communication access
F4 Reset	1 x Reset button
F5 Antenna	2 x SMA antenna holes (sealed by default)

## Embedded Computing Platform

### Rear I/Os

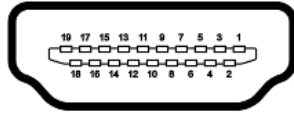


R1 Power Input	1 x2-pin terminal block, support DC +24V input
R2 Remote Power On/Off	1x 2pin terminal block for remote power on/off
R3 COM	4 x D-sub COM ports with RS-232/422/485 signals
R4 USB	2 x USB 2.0 Type-A ports in double-stacked form
R5 HDMI	2 x HDMI ports

## Chapter 3: Board Layout

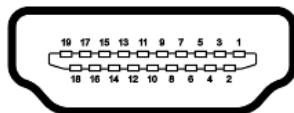
### Jumper Settings & Connector Pinout (Motherboard)

**HDMI1:** High-Definition Multimedia Interface connector



Pin No.	Description	Pin No.	Description
1	DATA2+	2	GND
3	DATA2-	4	DATA1+
5	GND	6	DATA1-
7	DATA0+	8	GND
9	DATA0-	10	CLK+
11	GND	12	CLK-
13	N.C	14	N.C
15	DDC CLK	16	DDC DAT
17	GND	18	HDMI_VCC
19	HPD		

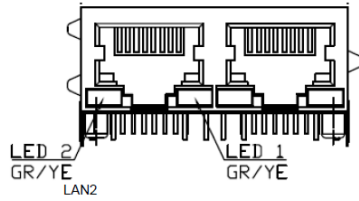
**HDMI2:** High-Definition Multimedia Interface connector



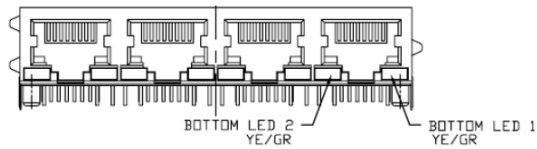
Pin No.	Description	Pin No.	Description
1	DATA2+	2	GND
3	DATA2-	4	DATA1+
5	GND	6	DATA1-
7	DATA0+	8	GND
9	DATA0-	10	CLK+
11	GND	12	CLK-
13	N.C	14	N.C
15	DDC CLK	16	DDC DAT
17	GND	18	HDMI_VCC
19	HPD		

## Embedded Computing Platform

**LAN1-6:** LAN Connectors (RJ-45 connectors with LED) at 10/100/1000Mbps for Ethernet connectivity. LAN3 to LAN6 are PoE ports.

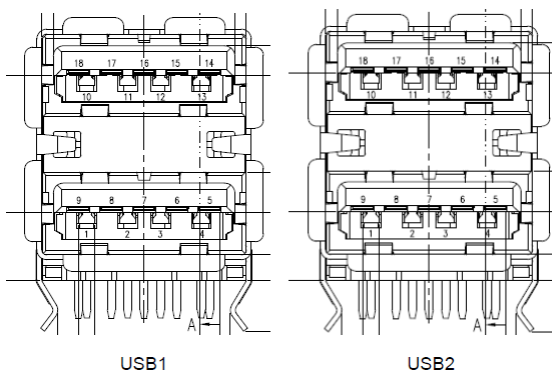


LAN2 Connector :LAN3/LAN4/LAN5/LAN6



Pin No.	Description	
1	TXD+	MD0+
2	TXD-	MD0-
3	RX+	MD1+
4	T45	MD2+
5	T45	MD2-
6	RX-	MD1-
7	T78	MD3+
8	T78	MD3-
9	10-/100-/1000+	
10	10+/100+/1000-	
11	Active LED+	
12	Active LED- ( yellow )	

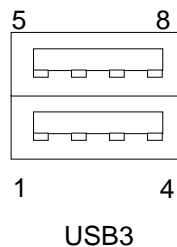
**USB1-2:** 4 x USB3.0 Type-A Connectors in dual double-stacked form



## Embedded Computing Platform

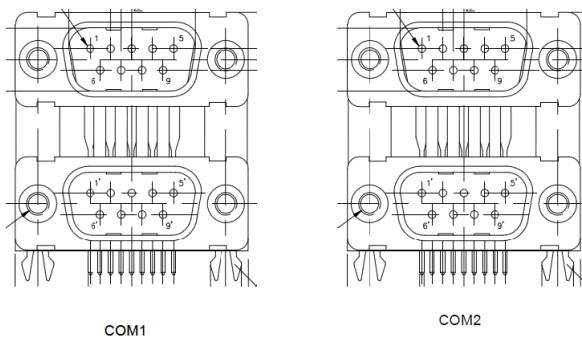
Pin No.	Description	Pin No.	Description
1	USB_VCC1	2	USB1_D-
3	USB1_D+	4	GND
5	USB1_RX-	6	USB1_RX+
7	GND	8	USB1_TX-
9	USB1_TX+	10	USB_VCC1
11	USB1_D-	12	USB1_D+
13	GND	14	USB1_RX-
15	USB1_RX+	16	GND
17	USB1_TX-	18	USB1_TX+

**USB3:** USB2.0 Type-A Connectors in double-stacked form



PIN NO.	DESCRIPTION
1	USB_VCC1
2	-USB
3	+USB
4	GND
0	USB_VCC2
6	-USB
7	+USB
8	GND

**COM1/COM2:** 4 x DB-9 COM ports with RS-232/422/485 signals (COM1-4 on the panel)





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Pin	Signal	Pin	Signal
1	Data Carrier Detect (DCDA#)	6	Data Set Ready (DSRA#)
2	Receive Data (RXDA)	7	Request To Send (RTSA#)
3	Transmit Data (TXDA)	8	Clear To Send (CTSA#)
4	Data Terminal Ready (DTRA#)	9	Ring Indicator (RIA#)
5	GND		

### RS-232/422/485

Pin	RS-232	RS-422	RS-485
1	DCD	TX-	RTX-
2	RXD	TX+	RTX+
3	TXD	RX+	
4	DTR	RX-	
5	GND		
6	DSR		
7	RTS		
8	CTS		
9	RI		

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**MPCIE1:** mini-PCIe slot with USB signals and SIM card reader (Full Size) for wireless module

Pin	Description	Pin	Description
1	WAKE#	2	+3.3V
3	RSVD	4	GND
5	RSVD	6	+1.5V
7	CLKREQ#	8	UIM_PWR
9	GND	10	UIM_DATA
11	REFCLK-	12	UIM_CLK
13	REFCLK+	14	UIM_RESET
15	GND	16	UIM_VPP

KEY

17	RSVD	18	GND
19	RSVD	20	W_DISABLE#
21	GND	22	PERST#
23	PERn0	24	+3.3V
25	PERp0	26	GND
27	GND	28	+1.5V
29	GND	30	SMB_CLK
31	PETn0	32	SMB_DATA
33	PETp0	34	GND
35	GND	36	USB_D+
37	GND	38	USB_D-
39	+3.3V	40	GND
41	+3.3V	42	LED_WWAN#
43	GND	44	LED_WLAN#
45	RSVD	46	LED_WPAN#
47	RSVD	48	+1.5V
49	RSVD	50	GND
51	RSVD	52	+3.3V



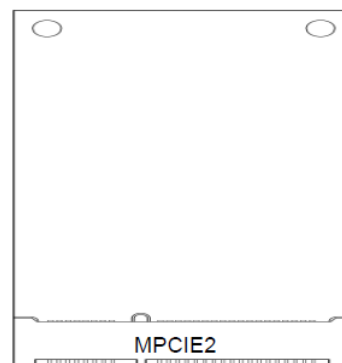
## Embedded Computing Platform

**MPCIE2:** half-sized mini-PCIe slot with PCIe and USB signals for wireless modules

Pin	Description	Pin	Description
1	WAKE#	2	+3.3V
3	RSVD	4	GND
5	RSVD	6	+1.5V
7	CLKREQ#	8	UIM_PWR
9	GND	10	UIM_DATA
11	REFCLK-	12	UIM_CLK
13	REFCLK+	14	UIM_RESET
15	GND	16	UIM_VPP

### KEY

17	RSVD	18	GND
19	RSVD	20	W_DISABLE#
21	GND	22	PERST#
23	PERn0	24	+3.3V
25	PERp0	26	GND
27	GND	28	+1.5V
29	GND	30	SMB_CLK
31	PETn0	32	SMB_DATA
33	PETp0	34	GND
35	GND	36	USB_D+
37	GND	38	USB_D-
39	+3.3V	40	GND
41	+3.3V	42	LED_WWAN#
43	GND	44	LED_WLAN#
45	RSVD	46	LED_WPAN#
47	RSVD	48	+1.5V
49	RSVD	50	GND
51	RSVD	52	+3.3V



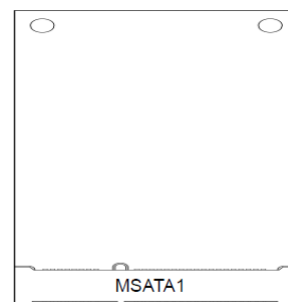
## Embedded Computing Platform

**MSATA1:** mSATA mini slot for storage device (half-sized form)

Pin	Description	Pin	Description
1	N.C	2	+3.3V
3	N.C	4	GND
5	N.C	6	N.C
7	N.C	8	N.C
9	GND	10	N.C
11	N.C	12	N.C
13	N.C	14	N.C
15	GND	16	N.C

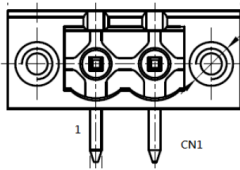
### KEY

17	N.C	18	GND
19	N.C	20	N.C
21	GND	22	N.C
23	SATA_RXp	24	+3.3V
25	SATA_RXn	26	GND
27	GND	28	N.C
29	GND	30	N.C
31	SATA_TXn	32	N.C
33	SATA_TXp	34	GND
35	GND	36	N.C
37	GND	38	N.C
39	+3.3V	40	GND
41	+3.3V	42	N.C
43	GND	44	N.C
45	N.C	46	N.C
47	N.C	48	N.C
49	N.C	50	GND
51	N.C	52	+3.3V



## Embedded Computing Platform

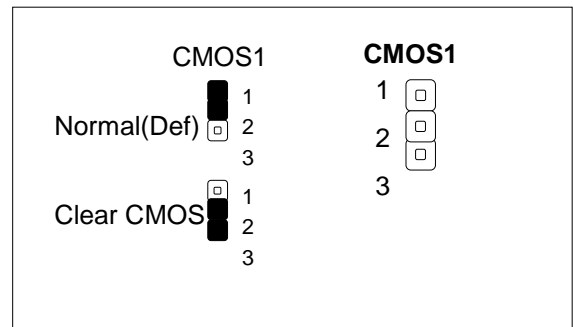
**DCIN1:** DC Power input through 2-pin 5.0mm Phoenix connector



PIN	DESCRIPTION
1	DC_IN (-)
2	DC_IN (24V)

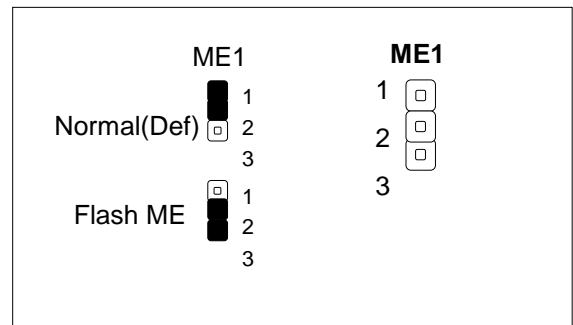
**JCMOS1:** Clear CMOS setting

Short Pins	Description
1-2	Normal (Default)
2-3	Clear CMOS

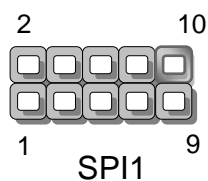


**JME1:** flash ME (Manageability Engine)

Short Pins	Description
1-2	Normal (Default)
2-3	Flash ME



**SPI1:** SPIROM pin header for debug purpose



PIN	DESCRIPTION	PIN	DESCRIPTION
1	SPI_HOLD	2	N.C
3	SPI_CS#	4	SPI_VCC
5	SPI_MO	6	N.C
7	N.C	8	SPI_CLK
9	GND	10	SPI_MI

## Chapter 4: Hardware Setup

### Accessing the Inside of HVP300

To access some components and perform certain service procedures, you must perform the following procedures first.

**WARNING:**

- To reduce the risk of personal injury, electric shock, or damage to the equipment, please remove all power sources.
- Please wear ESD protected gloves before conducting the following steps.
- Do NOT pile items on top of the system to prevent damages due to this improper use. Lanner is not liable for damages caused by improper use of the product.

1. Power off HVP300 and remove the power cord.
2. Rotate and remove the four rubber pads at the bottom compartment.



2. Lift and open the chassis.



### Installing SO-DIMM Memory

The system is designed with two SO-DIMM sockets supporting up to 16GB DDR3L 1333/1600MHz. Please follow the steps below for proper installations.

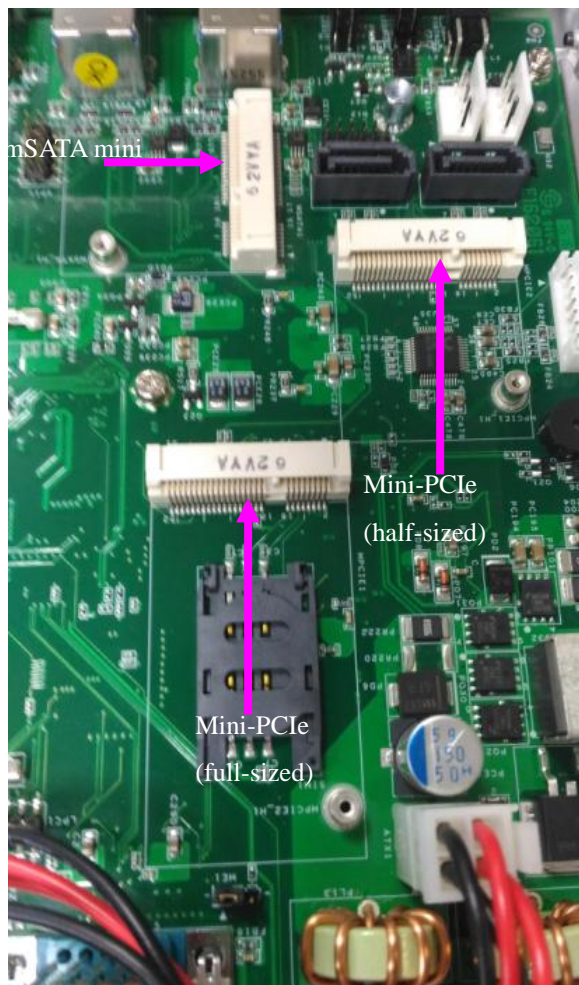
1. Locate the SO-DIMM sockets on the motherboard.
2. Select the socket for installing the module. Align the memory module's key with the SO-DIMM socket's key.
3. Insert the SO-DIMM module.
4. Press the module down until it is locked by the two clips at each side.



### Installing mSATA and Mini-PCIe Module

The system provides one mSATA mini socket and two mini-PCIe sockets (one full-sized and another half-sized) for storage and wireless modules. Please follow the steps below for installations.

1. Locate the mSATA and the mini-PCIe sockets.
2. Select the socket for installing the module. Align the mechanical notches between the module and the socket.
3. Insert the module into the socket.
4. Secure the installed module with two screws.

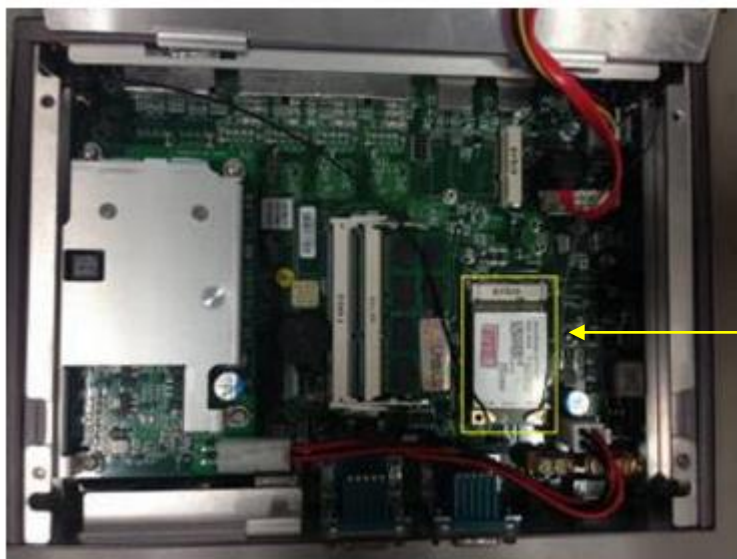




### Installing LTE Wireless Network Module

The mini-PCIe socket of the system is compatible with LTE wireless network module. Please follow the steps below for installations.

1. Locate the mini-PCIe sockets.
2. Align the mechanical notches between the module and the socket.
3. Insert the LTE wireless network module (Sierra M7354 in this case) into the socket.
4. Secure the installed module with two screws.



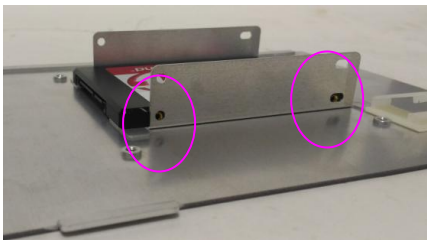
### Installing Disk Drives

The system supports 1 x dual 2.5" SATA HDD/SSD drive bay as data storage (SSD is recommended due to heat and vibration concerns). Please follow the steps below for installation.

1. Locate the dual 2.5" SATA HDD/SSD drive bay at the back of the bottom compartment.



2. Place disk drives onto the drive bay and apply two screws on each side of a SATA disk drive.



3. Connect the SATA 7-pin signal cable and the SATA 4-pin power cable to their corresponding connectors on the motherboard.



## Embedded Computing Platform

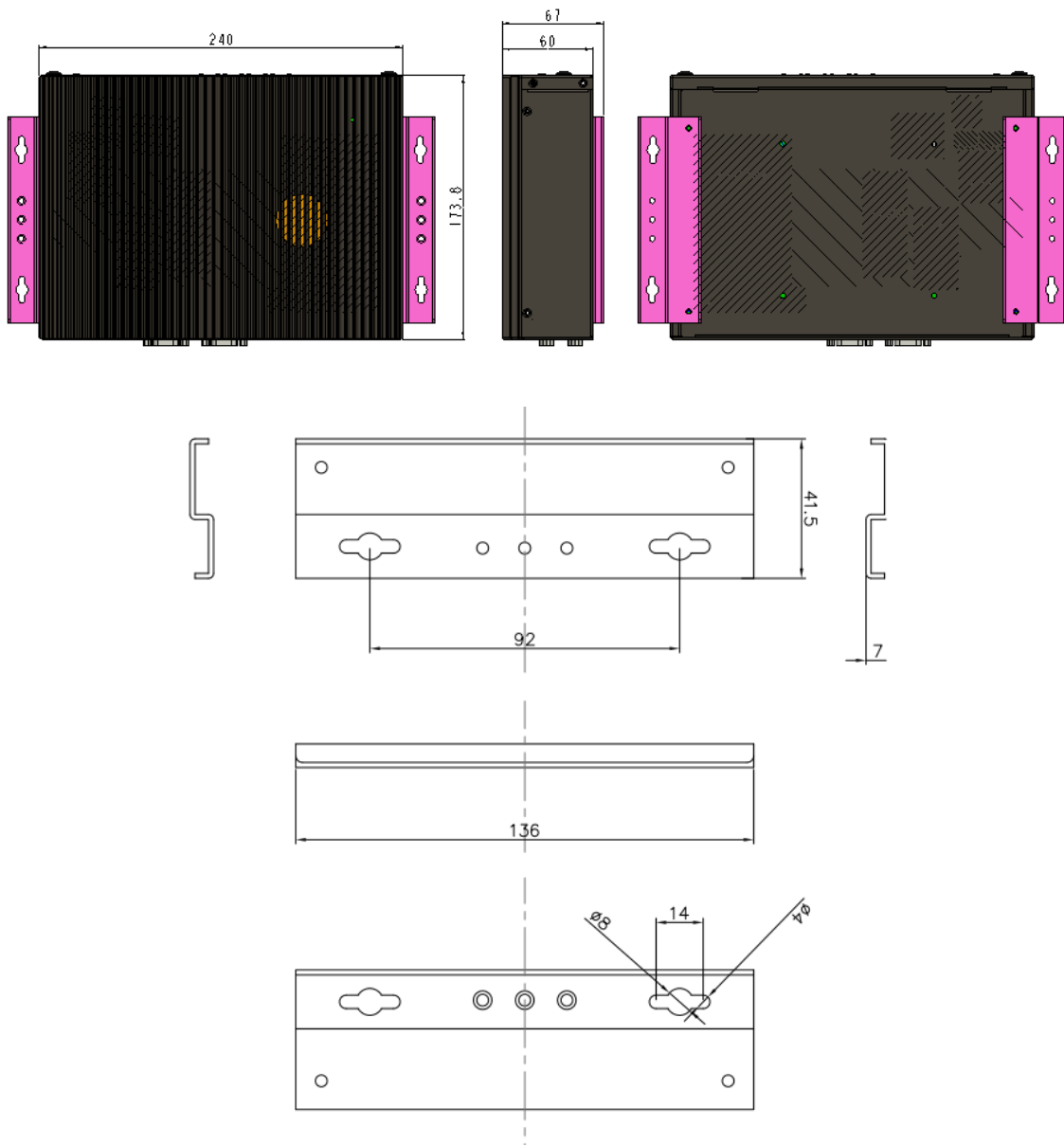
4. Plug the standard 7+15 SATA connector to the SSD.



### Wall Mounting

The system can be mounted on a flat surfaced wall. Please take the following into considerations when mounting the system onto the wall.

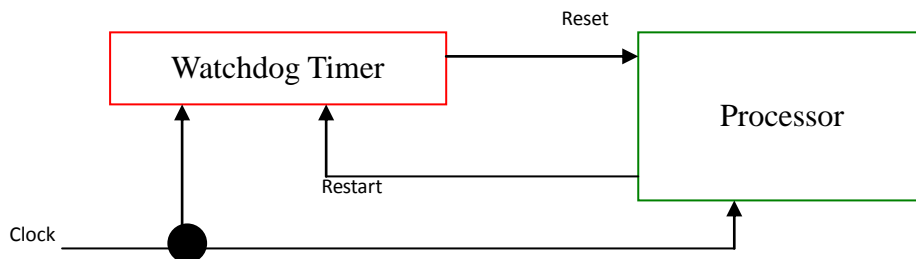
1. Ensure the wall brackets are properly fixed onto the chassis, as illustrated in the drawings below.
2. Please pay close attention to the dimensional parameters in the drawings below such as the distance between each screw hole of a bracket piece. The parameter values serve as important reference for applying standoffs on the wall.



## Appendix 1: Watchdog Timer

A watchdog timer is a piece of hardware that can be used to automatically detect system anomalies and reset the processor in case there are any problems. Generally speaking, a watchdog timer is based on a counter that counts down from an initial value to zero. The software selects the counter's initial value and periodically restarts it. Should the counter reach zero before the software restarts it, the software is presumed to be malfunctioning and the processor's reset signal is asserted. Thus, the processor will be restarted as if a human operator had cycled the power.

To download sample watchdog code, please refer to our official website at [www.lannerinc.com](http://www.lannerinc.com).



## Embedded Computing Platform

### Federal Communications Commission

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radiofrequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

FCC Caution: Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate this equipment.

This device complies with part 15 of the FCC Rules.

Operation is subject to the following two conditions:

- (1) This device may not cause harmful interference, and
- (2) this device must accept any interference received, including interference that may cause undesired operation.

### **Radiation Exposure Statement:**

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20cm between the radiator & your body.